

HZM6.8ZMWA

Silicon Planar Zener Diode for Surge Absorb

REJ03G1212-0200

(Previous: ADE-208-822A) Rev.2.00

Jun 14, 2005

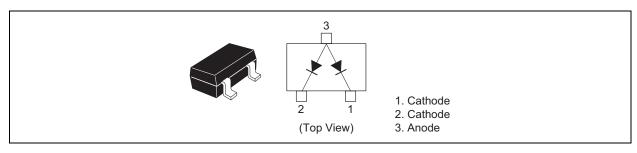
Features

- HZM6.8ZMWA has two devices in a monolithic, and can absorb surge.
- Low capacitance (C = 25 pF max) and can protect ESD of signal line.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZM6.8ZMWA	68N	MPAK	PLSP0003ZC-A (MPAK)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Power dissipation	Pd *1	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	−55 to +150	°C

Note: 1. Two device total, See Fig.2.

Electrical Characteristics *1

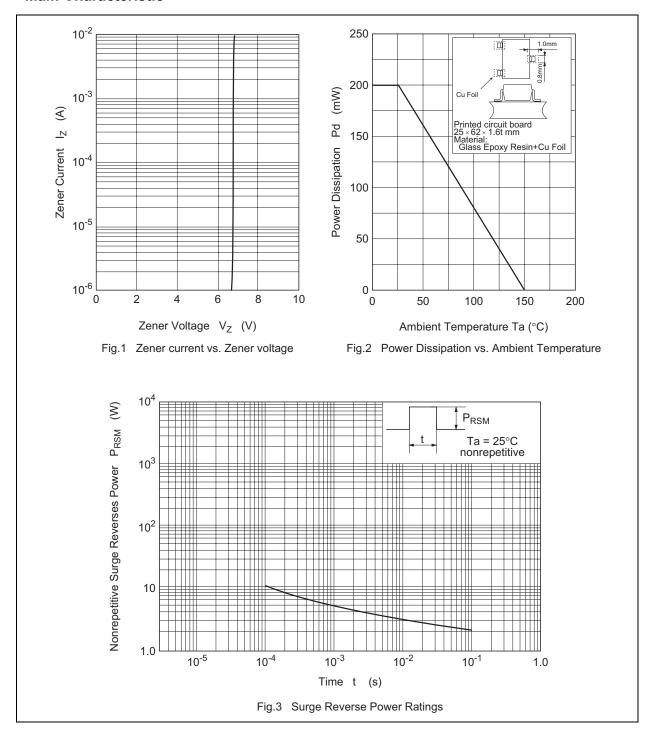
 $(Ta = 25^{\circ}C)$

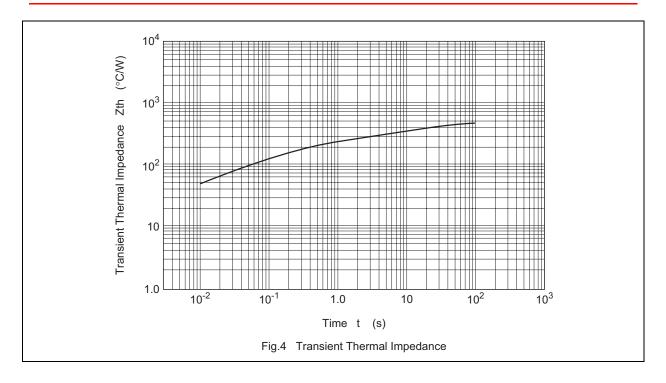
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	6.47	_	7.0	V	I_Z = 5 mA, 40 ms pulse
Reverse current	I _R	_	_	2	μΑ	V _R = 3.5 V
Capacitance	С	_	_	25	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r_d	_	_	30	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *2		20	_	_	kV	C = 150 pF, R = 330 Ω , Both forward and reverse direction 10 pulse

Notes: 1. Per one device

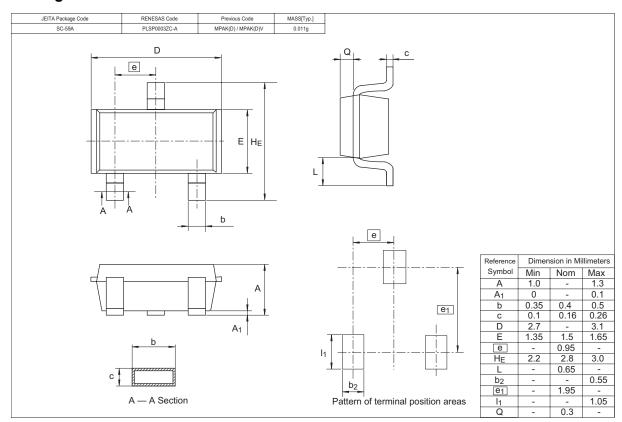
2. Failure criterion ; $I_R > 2~\mu\text{A}$ at V_R = 3.5 V.

Main Characteristic





Package Dimensions



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